

VCRR P-Channel Enhancement Mode Power MOSFET

Description

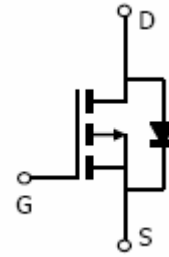
The VCRR55P12 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

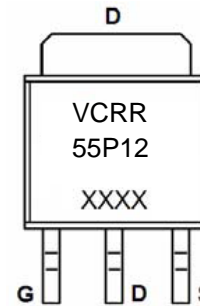
- $V_{DS} = -55V, I_D = -15A$
 $R_{DS(ON)} < 75m\Omega @ V_{GS} = -10V$
- High density cell design for ultra low R_{dson}
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- DC-DC Converter



Schematic diagram



Marking and pin assignment

Package Marking and Ordering Information

| Device Marking | Device | Device Package |
|----------------|--------|----------------|
| VCRR55P12 | | TO-252 |

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|--------------------|------------|------------|
| Drain-Source Voltage | V_{DS} | -55 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | -15 | A |
| Drain Current-Continuous($T_C = 100^\circ C$) | $I_D(100^\circ C)$ | -10 | A |
| Pulsed Drain Current | I_{DM} | -50 | A |
| Maximum Power Dissipation | P_D | 35 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 175 | $^\circ C$ |

Thermal Characteristic

| | | | |
|--|-----------------|-----|---------------|
| Thermal Resistance ,Junction-to-Case ^(Note 2) | $R_{\theta JC}$ | 4.3 | $^{\circ}C/W$ |
|--|-----------------|-----|---------------|

Electrical Characteristics ($T_C=25^{\circ}C$ unless otherwise noted)

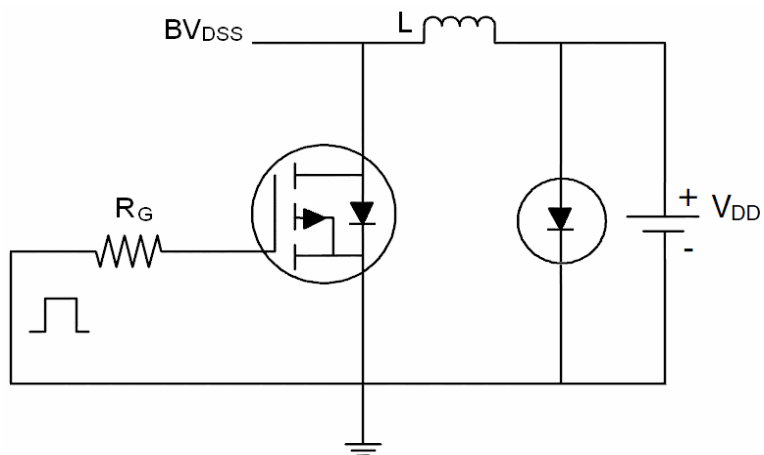
| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|--------------|---|------|------|-----------|------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=-250\mu A$ | -60 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=-55V, V_{GS}=0V$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| On Characteristics ^(Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -1.5 | -2.6 | -3.5 | V |
| Drain-Source On-State Resistance | $R_{DS(ON)}$ | $V_{GS}=-10V, I_D=-5A$ | - | 60 | 75 | m Ω |
| Forward Transconductance | g_{FS} | $V_{DS}=-15V, I_D=-5A$ | 16 | - | - | S |
| Dynamic Characteristics ^(Note 4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS}=-20V, V_{GS}=0V,$ $F=1.0MHz$ | - | 1450 | - | PF |
| Output Capacitance | C_{oss} | | - | 145 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | - | 110 | - | PF |
| Switching Characteristics ^(Note 4) | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=-30V, R_L=30\Omega$ $V_{GS}=-10V, R_{GEN}=6\Omega$ | - | 8 | - | nS |
| Turn-on Rise Time | t_r | | - | 9 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 65 | - | nS |
| Turn-Off Fall Time | t_f | | - | 30 | - | nS |
| Total Gate Charge | Q_g | $V_{DS}=-30V, I_D=-5A,$ $V_{GS}=-10V$ | - | 26 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 4.5 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 7 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage ^(Note 3) | V_{SD} | $V_{GS}=0V, I_S=-15A$ | - | - | 1.2 | V |
| Diode Forward Current ^(Note 2) | I_S | | - | - | -15 | A |

Notes:

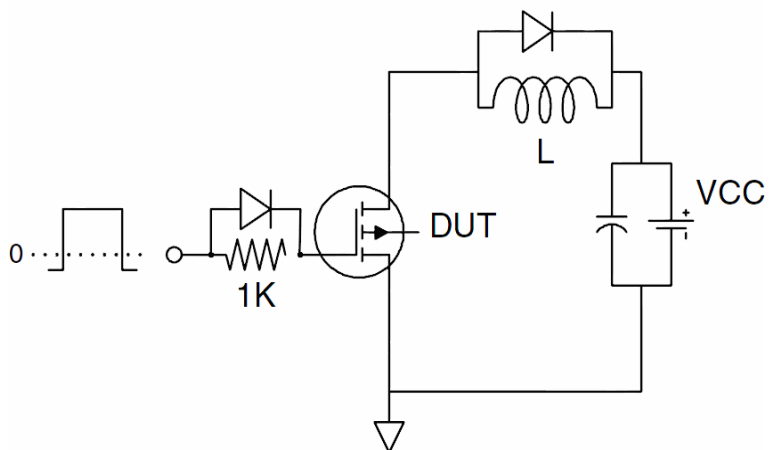
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Test Circuit

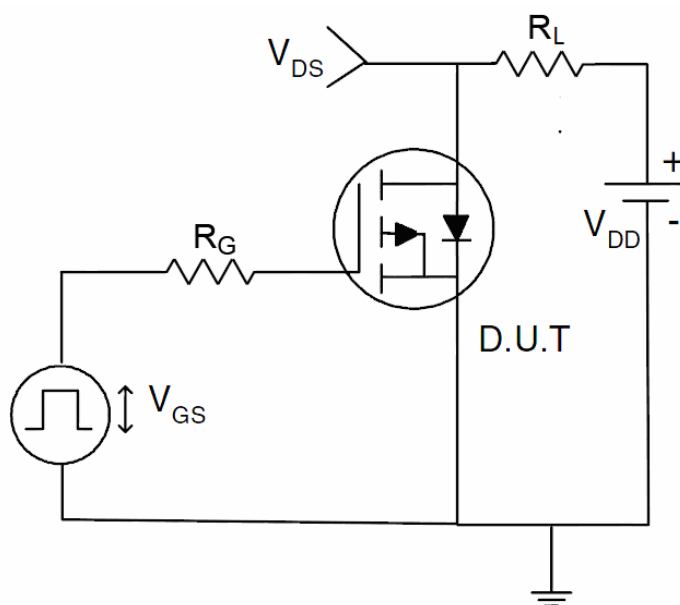
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

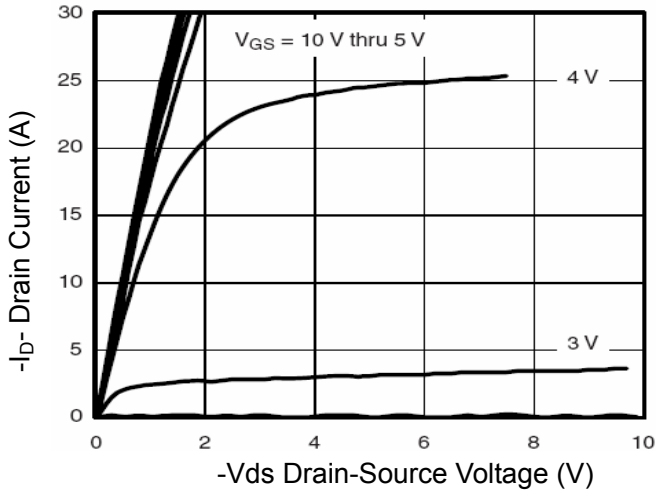


Figure 1 Output Characteristics

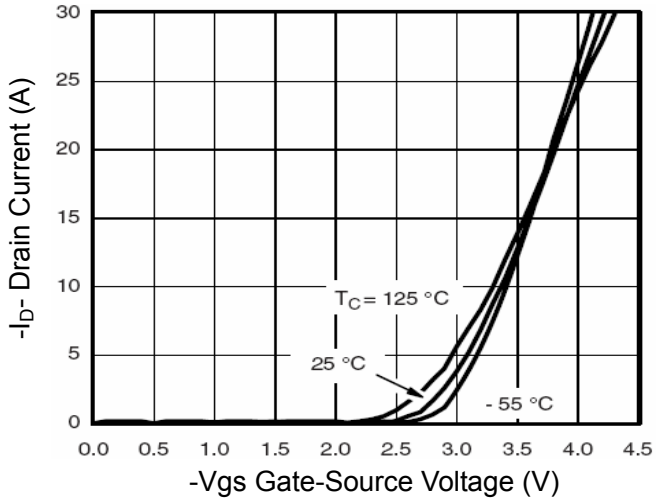


Figure 2 Transfer Characteristics

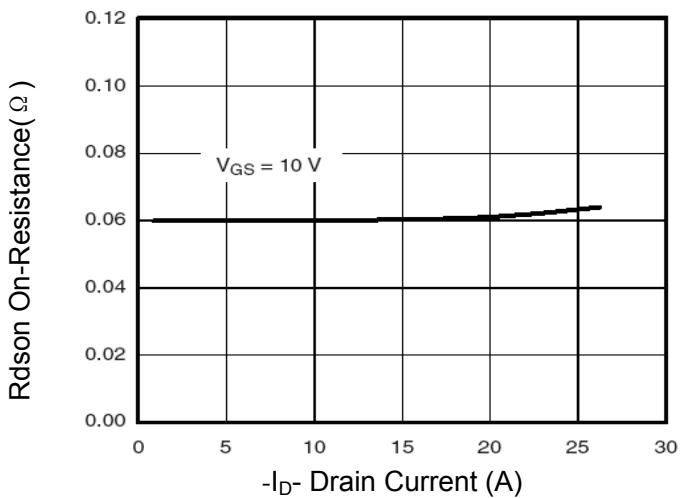


Figure 3 Rds(on)- Drain Current

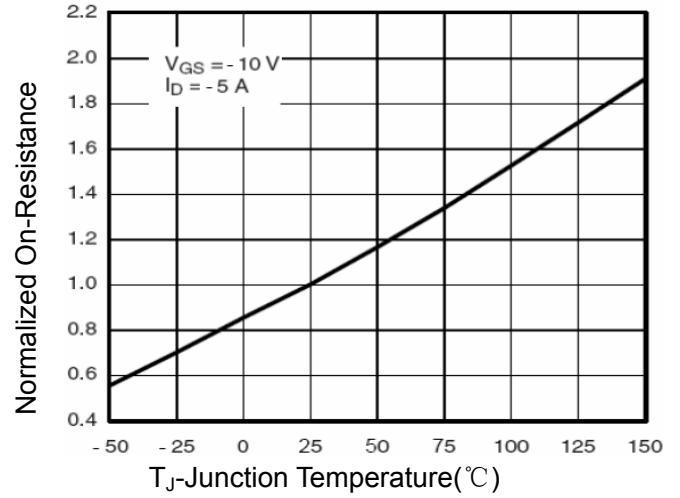


Figure 4 Rds(on)-Junction Temperature

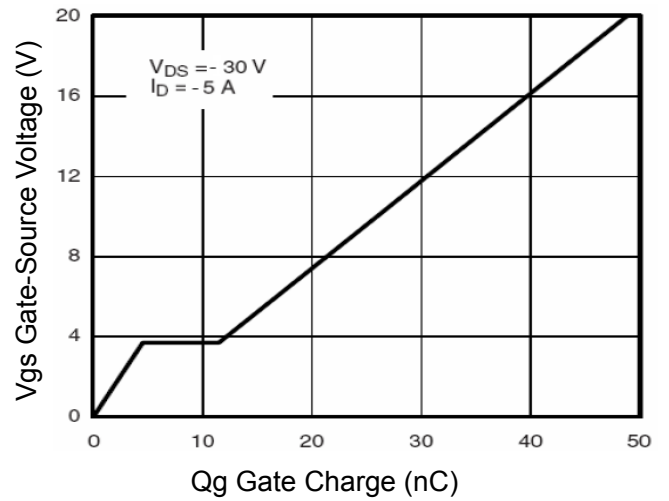


Figure 5 Gate Charge

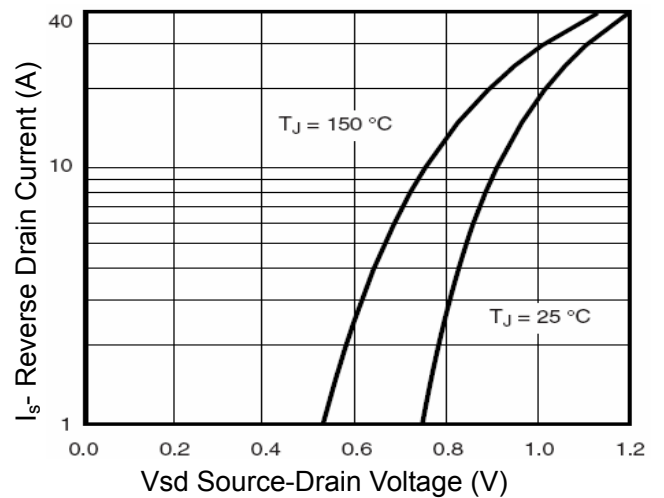


Figure 6 Source- Drain Diode Forward

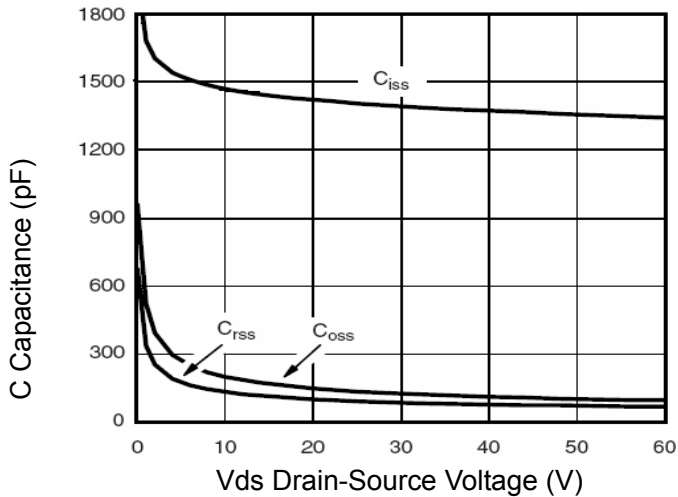


Figure 7 Capacitance vs Vds

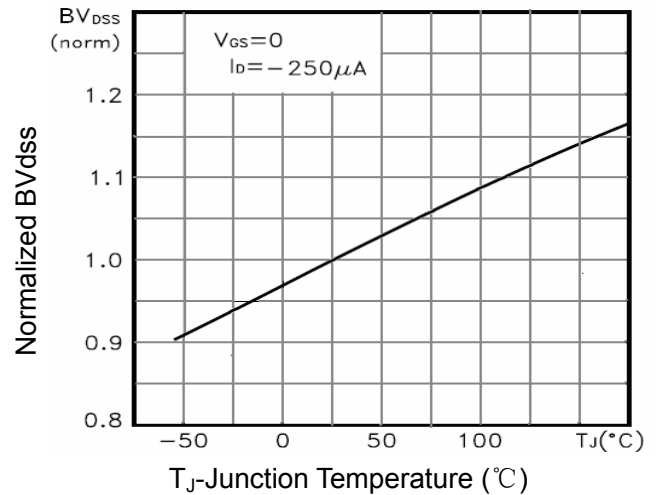


Figure 9 BV_{DSS} vs Junction Temperature

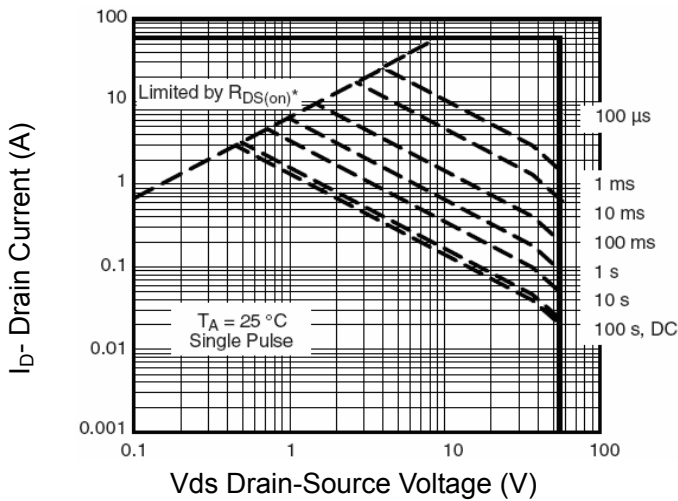


Figure 8 Safe Operation Area

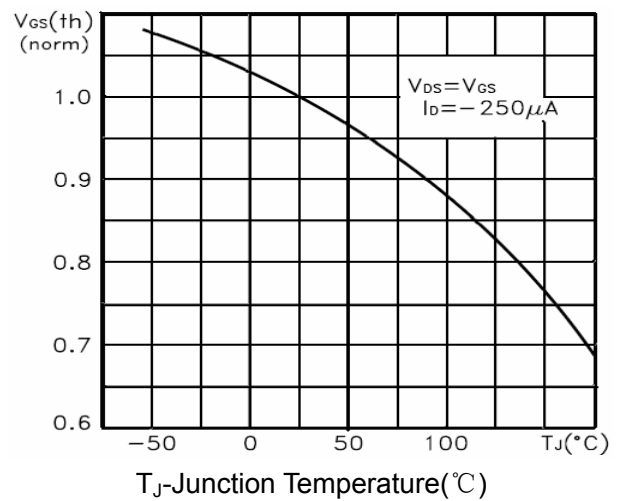


Figure 10 V_{GS(th)} vs Junction Temperature

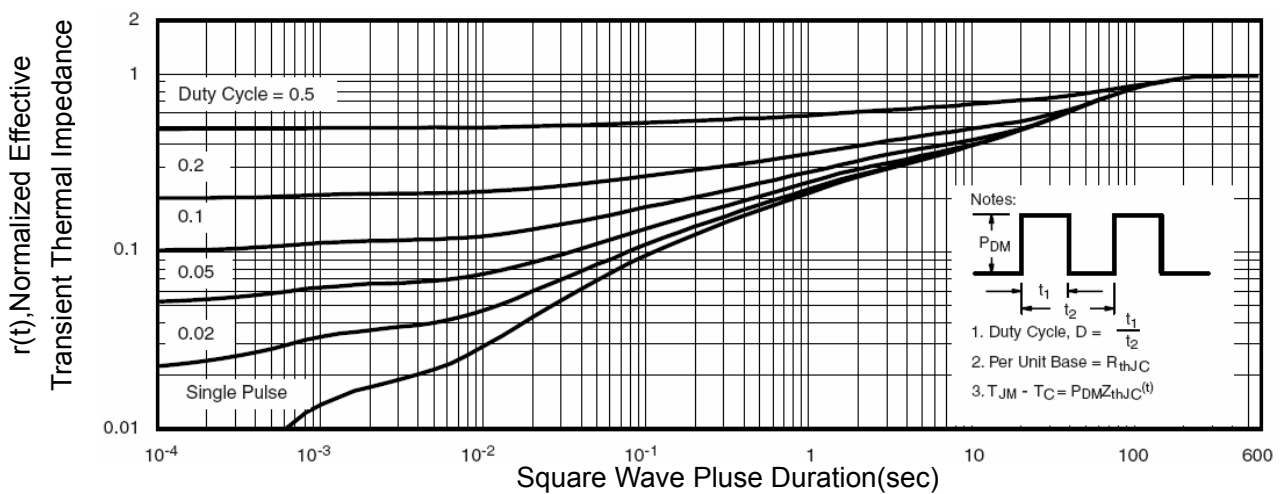
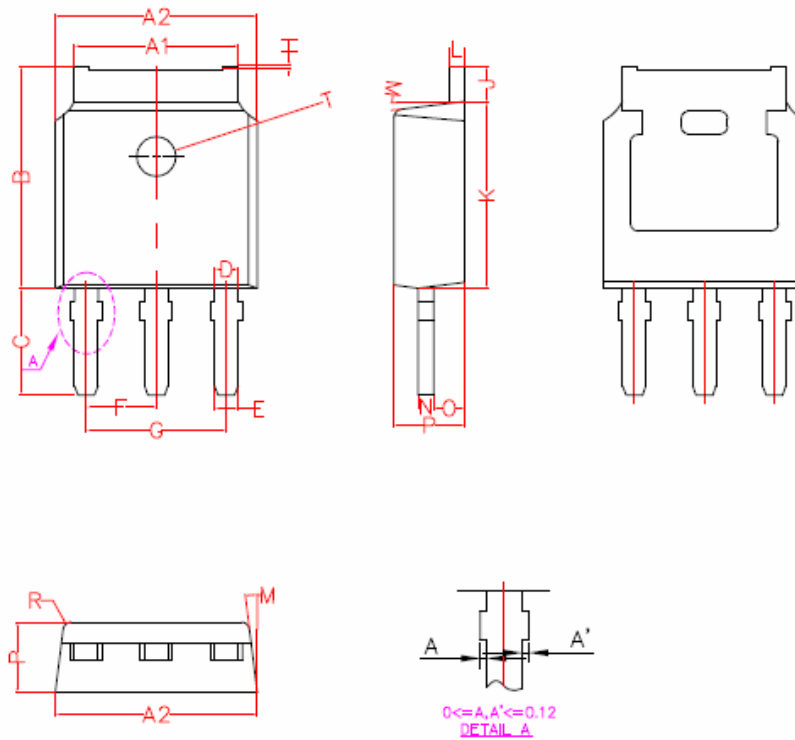


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-251 Package Information



| Symbol | Min | Non | Max |
|--------|------|-------|------|
| A1 | 5.22 | 5.32 | 5.42 |
| A2 | 6.55 | 6.60 | 6.65 |
| B | 7.05 | 7.10 | 7.15 |
| C | 4.80 | 5.00 | 5.20 |
| D | | 1.00 | |
| E | | 0.76 | |
| F | | 2.286 | |
| G | | 4.572 | |
| H | | 0.15 | |
| J | 0.95 | 1.00 | 1.05 |
| K | 6.05 | 6.10 | 6.15 |
| L | | 0.508 | |
| M | | 7° | |
| N | | 0.508 | |
| O | 0.96 | 1.01 | 1.06 |
| P | 2.25 | 2.30 | 2.35 |
| R | | 0.25 | |

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